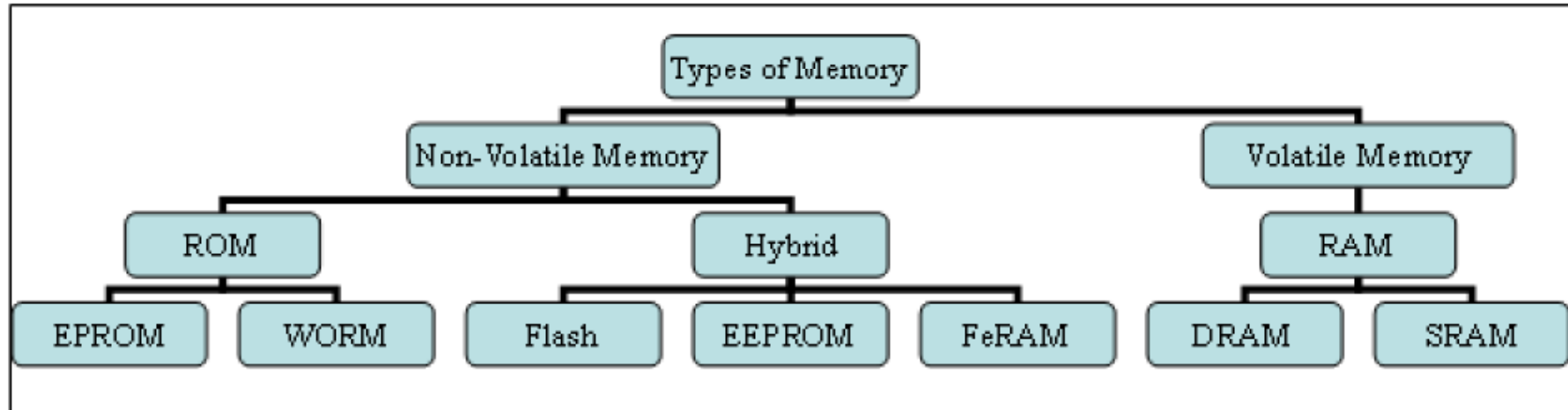


# **Polymer Electronic Memories: Materials, Devices and Mechanisms**

Chunxiang Zhu  
Dept of Electrical and Computer Engineering  
National University of Singapore



**ROM:** Read Only Memory

**EPROM:** Electrically Programmable Read-Only Memory

**WORM:** Write-Once Read-Many-Times

**Flash:** Rewritable

**EEPROM:** Electrically Erasable Programmable Read-Only Memory

**FeRAM:** Ferroelectric Random Access Memory

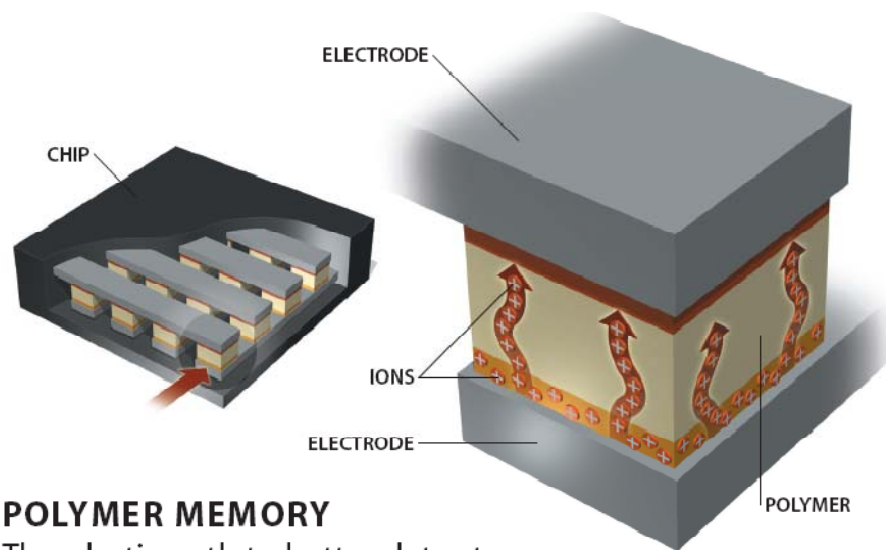
**RAM:** Random Access Memory

**DRAM:** Dynamic Random Access Memory

**SRAM:** Static Random Access Memory

## Stimuli-Responsive Polymers for Information Storage

Rather than encoding “0” and “1” as the amount of charge stored in a Si cell, a polymer memory stores data in another form, for instance, based on the high and low conductivity response to an applied voltage (electrical bistability)



**POLYMER MEMORY**

The plastic path to better data storage



**Multi-layer construction**

# Classification of Polymer Memories



## Mechanistic Analogy Between the Polymer Memory Elements and the 3 Primary Circuit Elements

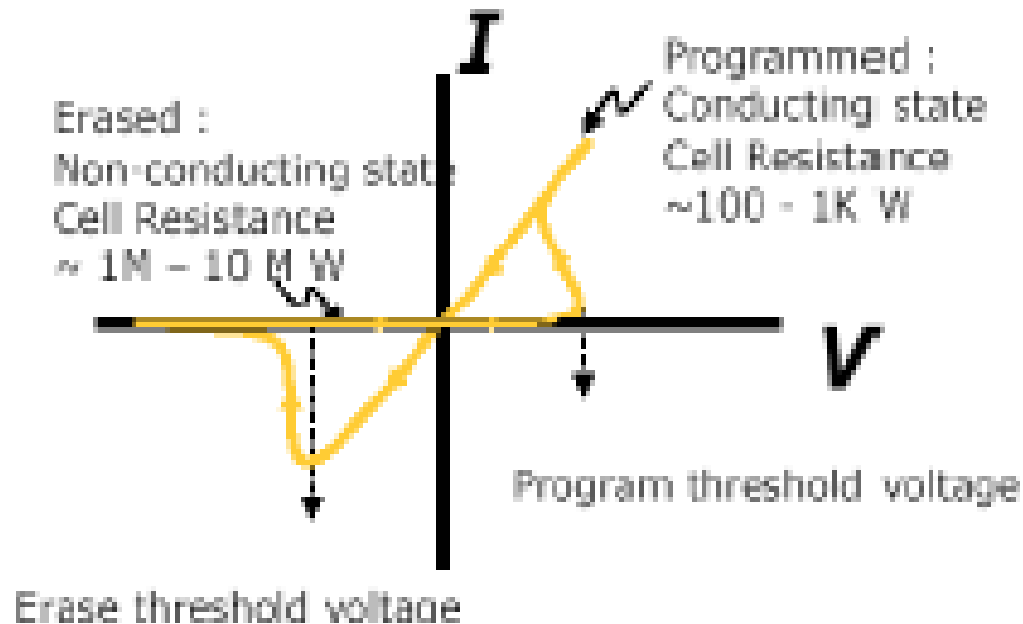
Type	Capacitor-type polymer memories	Transistor-type polymer memories	Resistor-type polymer memories
Physical description	The capacitor stores charges, of opposite sign, on two parallel plate electrodes, indicating the bit level. Each bit of data is stored in a separate capacitor.	Charge storage and polarization in the dielectric layer or interfaces of an organic field effect transistor, indicating the bit level of an OFET memory.	Data storage is based on the high and low conductivity states (electrical bistability) of resistor in response to the applied electric field.
Device structure	(a) 1 Transistor + 1 Capacitor (1T1C) (b) 1 Transistor + 2 Capacitor (1T2C) (c) 2 Transistor + 2 Capacitor (2T2C)	(a) Floating gate OFET (b) Charge trapping OFET (c) Ferroelectric OFET	(a) Metal-Insulator-Metal (MIM) (b) Cross-point array memory (c) 3D (three-dimensional) stacking
Polymer materials	<b>Ferroelectric polymers:</b> (a) PVDF or P(VDF-TrFE) (b) Odd nylons (c) Cyanopolymers (d) Polyureas and polythioureas (e) FLC polymers	<b>Semiconductor materials:</b> $\pi$ -Conjugated molecules and polymers. <b>Gate insulator (electrets):</b> Inorganic insulators, discrete metal nanoparticles, polymer dielectrics, ferroelectric polymers	(a) Insulating polymers (b) Isolated chromophores, donors and acceptors (c) Semiconducting polymers (d) Composite materials
Mechanism	Ferroelectric polymer can maintain permanent electric polarization that can be repeatedly switched between two stable states by an external electric field.	Charge storage or polarization in OFET gives rise to an additional voltage between the gate and the semiconductor channel, and a shift of $V_{th}$ or hysteresis.	Electrical bistability can be induced by (a) a change in carrier concentration, (b) a change in charge mobility, and (c) a change in both.
Performance factors	Polymer composition, crystallinity, film thickness, switching dynamics, film defects, metal electrodes, field pulses, fatigue characteristics	Charge mobility, capacitance per area, maximum electric displacement, impurity, morphology, crystal packing, energy barrier, deposition conditions	Filamentary conduction, space charges and traps, charge transfer (CT) effects, tunnelling, conformation changes, polymer fuse effects, ionic conductions
Technical Limitations	(a) Destructive read-out (b) Material degradation (c) Capacitor scaling	(a) Thickness control of dielectric layer (b) Parasitic capacitance (c) Charge coupling	(a) Mechanisms unascertained (b) Reproducibility (c) Parasitic leakage current

# Resistive Random Access Memory (RRAM)

**Data Storage Based on Electrical Bistability (ON- and OFF-states) of Materials Arising from Changes in Intrinsic Properties, e.g., CT, Phase/Conformation Change and Redox, in Response to the Applied Electric Field (not based on a specific cell structure, e.g., FET, or Si CMOS technology)**

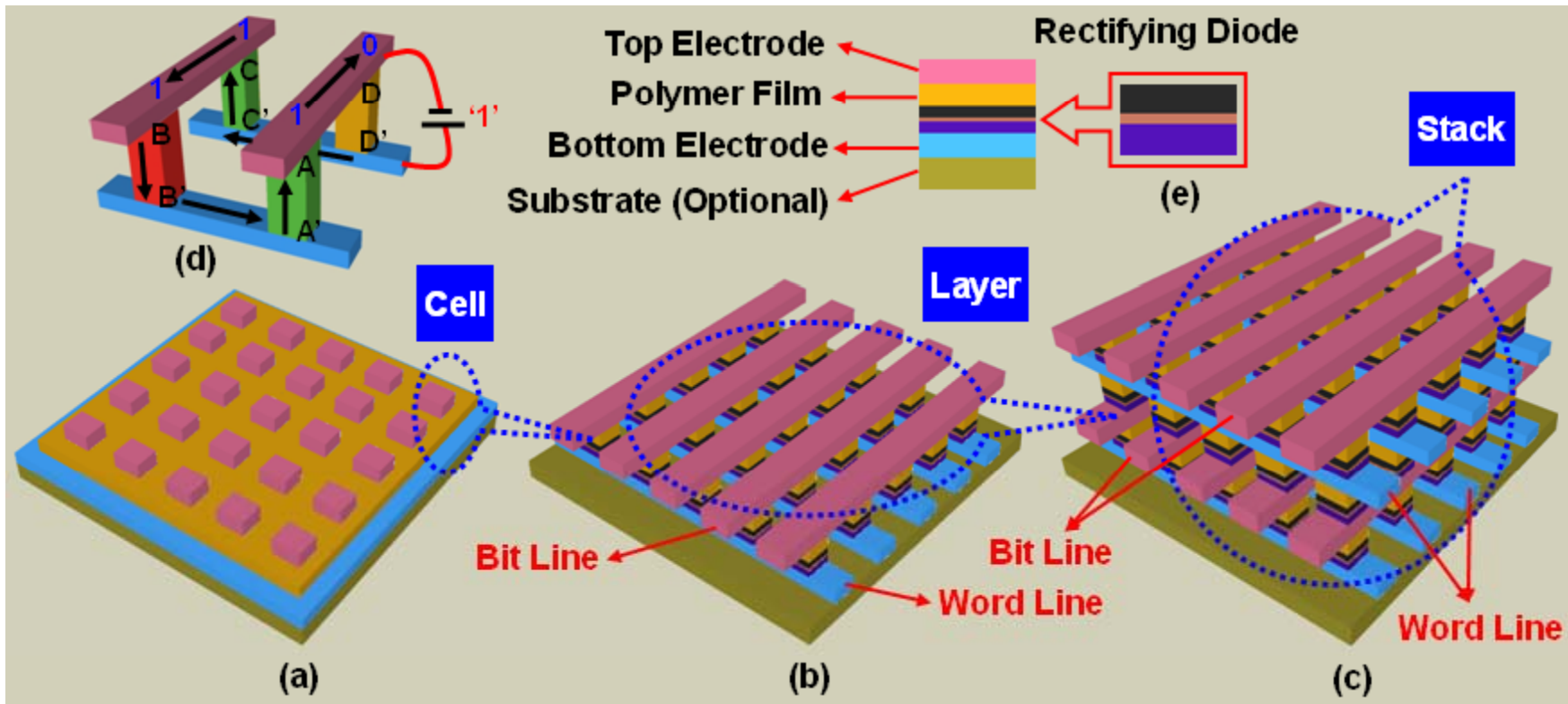
**Polymeric material serving as a fuse:**

- Write a bit with high current (blow the fuse)**
- Read a bit with low current (check to see if the fuse is blown)**
- Rewritable memories use reversible fuse states**



# Resistive Random Access Memory (RRAM)

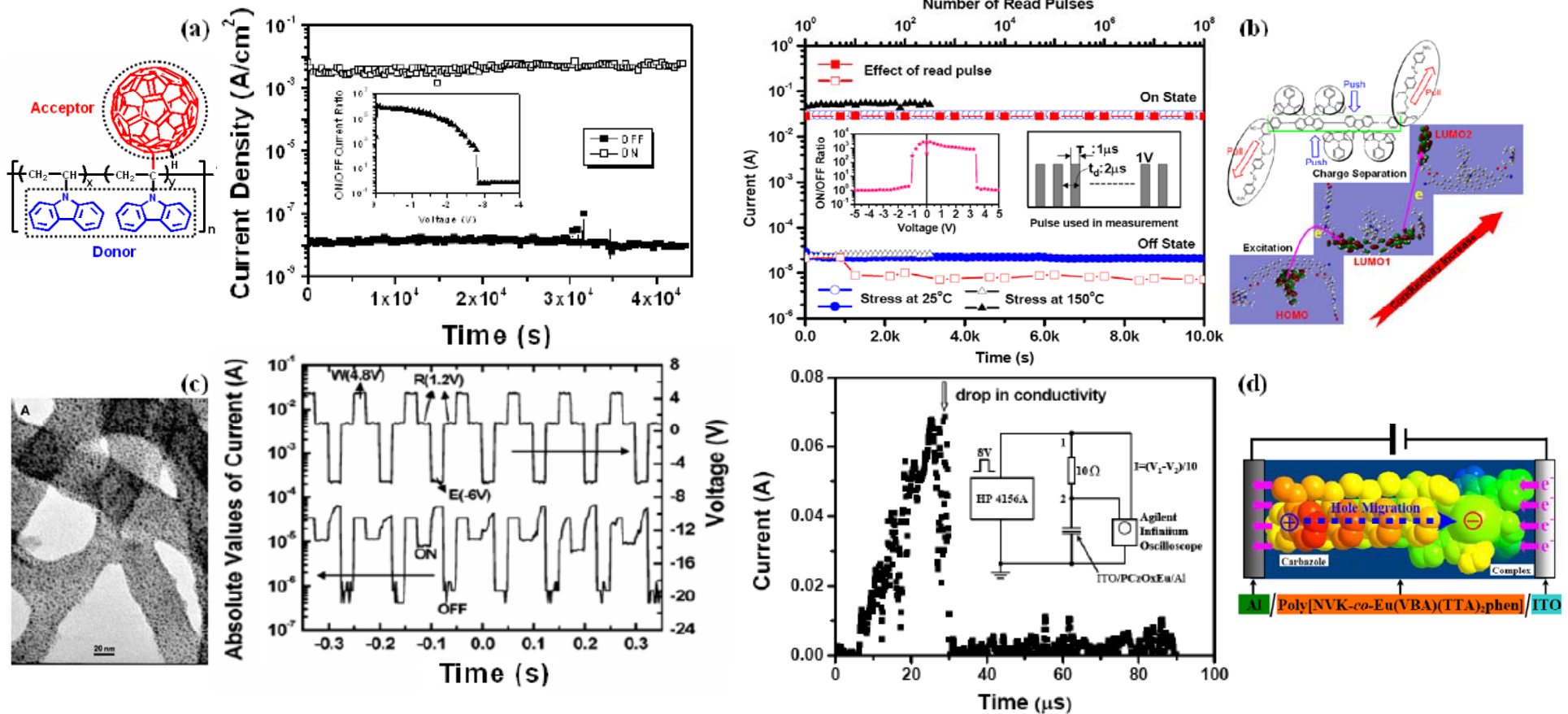
## General Device Structures



- (a) 5 × 5 testing polymer devices and the basic configuration of a memory cell,
- (b) a 5 (Word line) × 5 (Bit line) cross-point memory array,
- (c) a 2 (Stacked layer) × 5 (Word line) × 5 (Bit line) stacked memory device,
- (d) parasitic paths in cross-point memories, and
- (e) rectifying diode integrated to avoid parasitic currents.

# Resistive Random Access Memory (RRAM)

## Evaluation parameters for molecular/polymer memories

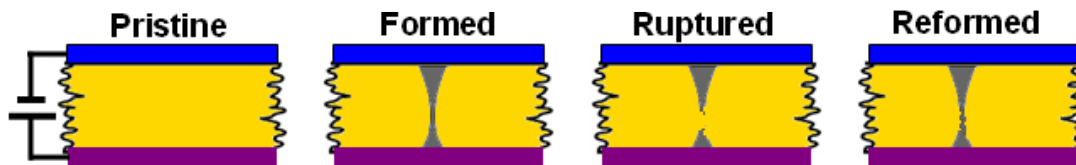


- (a) Stability under voltage stress and ON/OFF ratio (inset) [PVK-C<sub>60</sub>, *Langmuir* 2007 23 312]
- (b) Thermal stress and number of read pulses [Conjugated triad, *Appl Phys Lett* 2008 92 143302]
- (c) Write-read-erase-read (WRER) cycles [PANI nf-Au np, Y Yang et al. *Nano Lett* 2005 5 1077]
- (d) Switching time measurement [PVK-Eu copolymer, *Adv Mater* 2005 17 455].

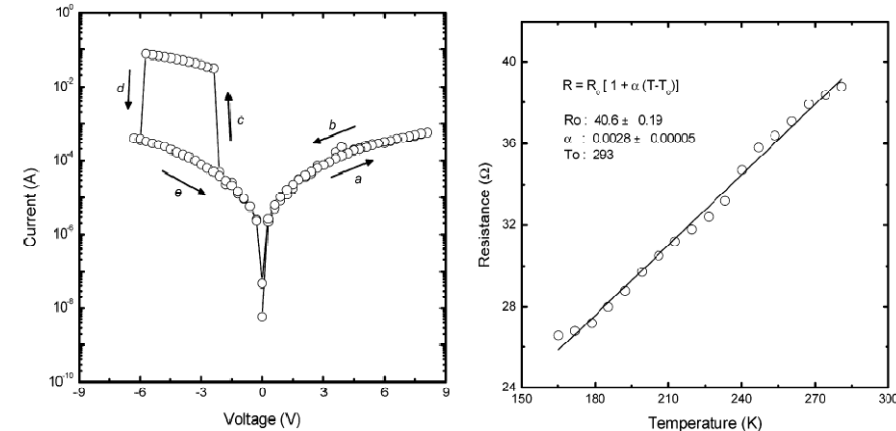
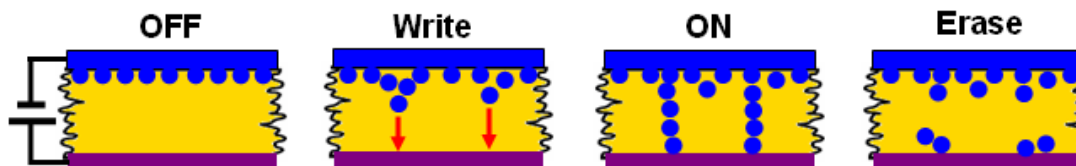
# Resistive Random Access Memory (RRAM)

## RRAM from Filamentary Conduction

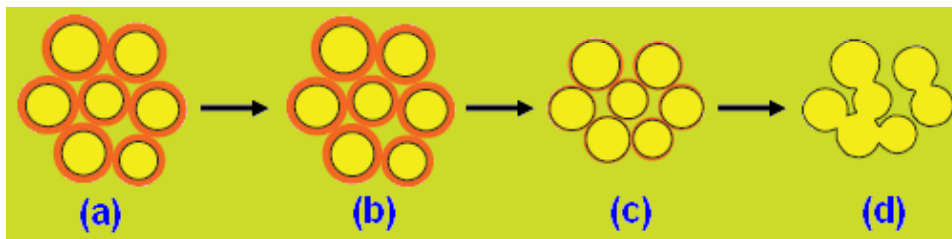
(a) Carbon-rich filaments



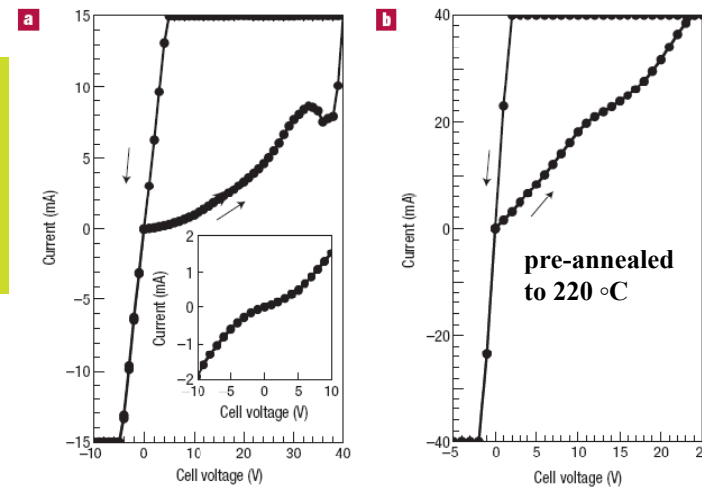
(b) Metallic filaments



I-V curve and temp-dependent R of regioregular P3HT device attributable to metal filaments [Joo et al. *J Phys Chem B* 2006 110 23812]



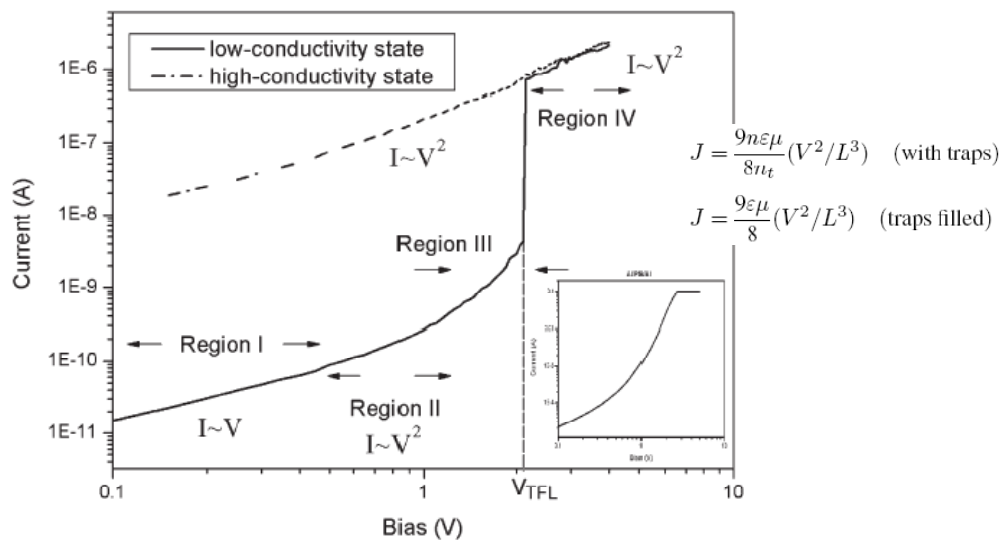
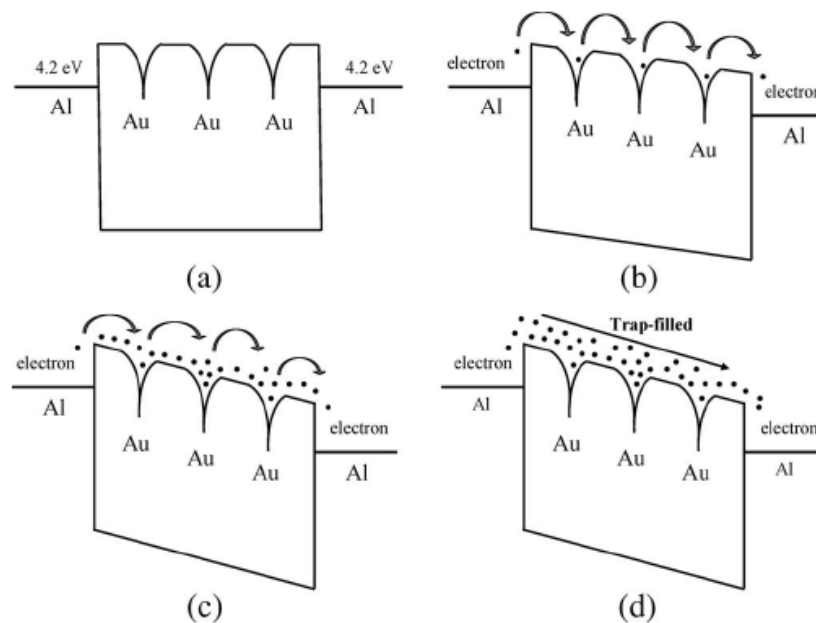
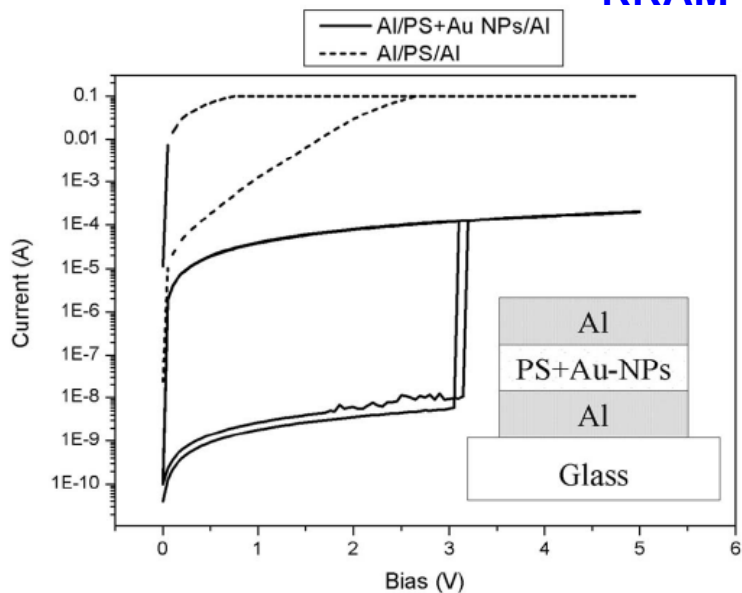
Metallic filaments from controlled insulator-metal transformation of Au nanoclusters [Ho et al. *Nature Mater* 2007 6 149]





# Resistive Random Access Memory (RRAM)

## RRAM from Space Charges and Traps



*H T Lin et al. IEEE Electron Dev Lett 2007 28 569*

# Resistive Random Access Memory (RRAM)

## RRAM from Space Charges and Traps Poly(*N*-vinylcarbazole)-Carbon Nanotube Composite Films

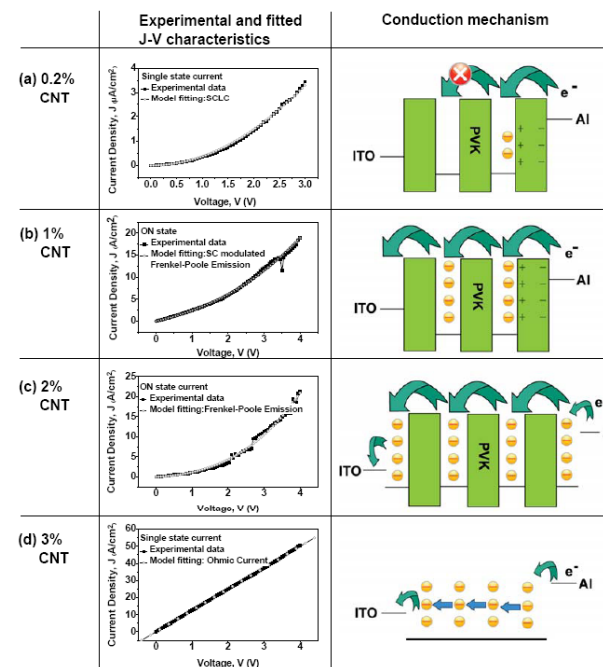
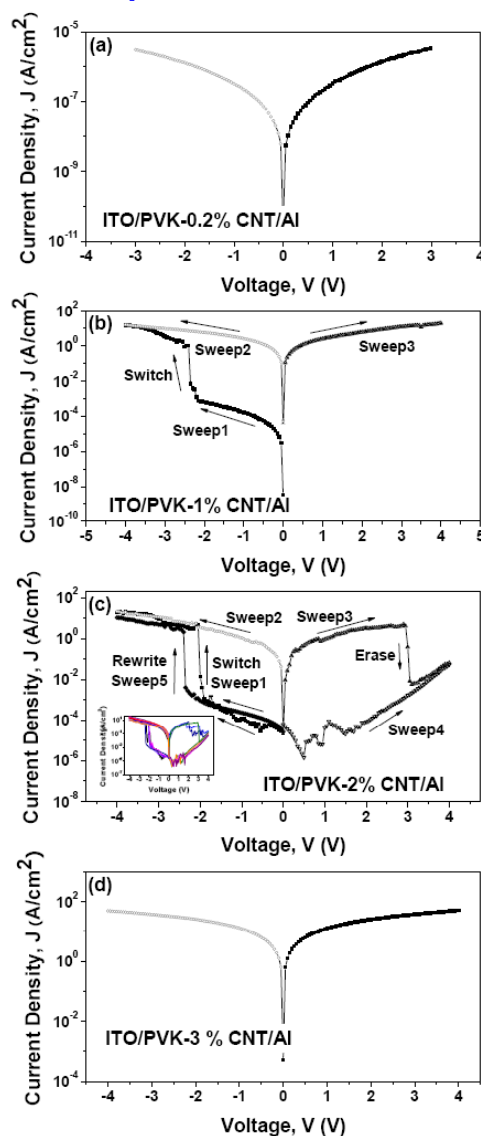
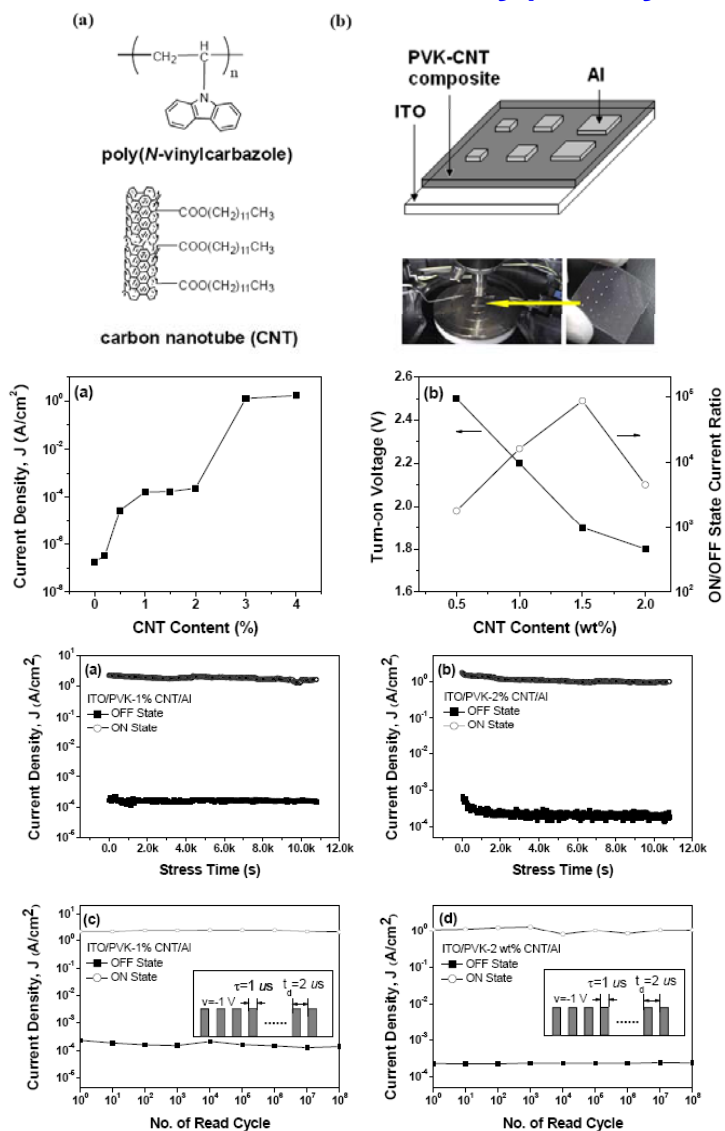


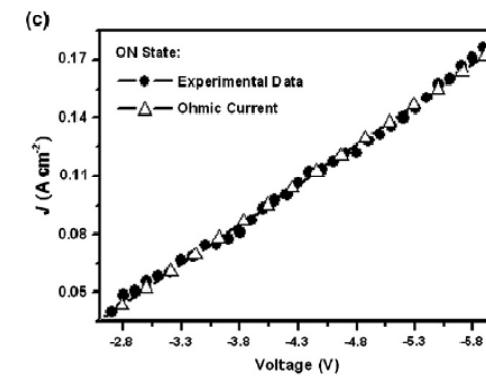
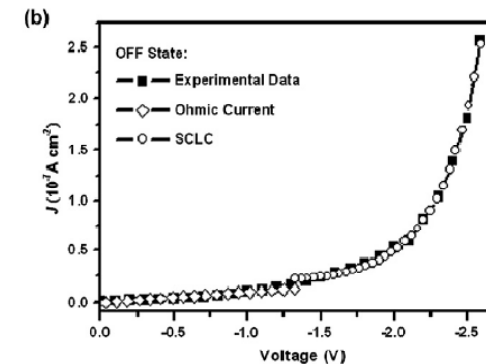
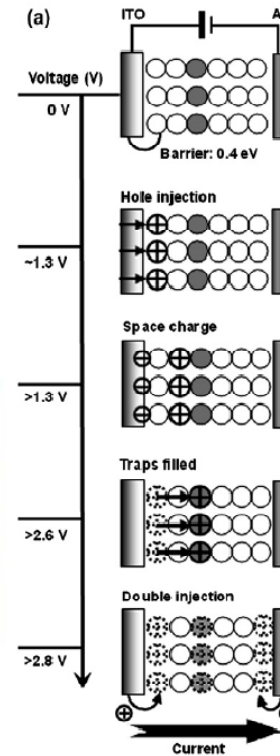
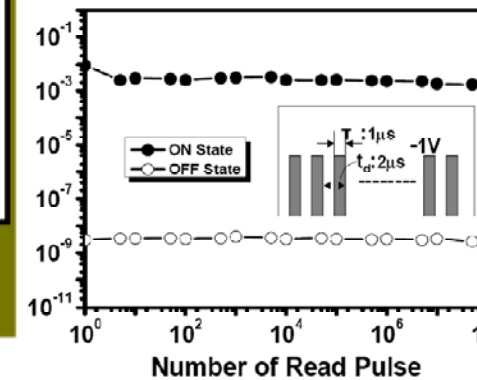
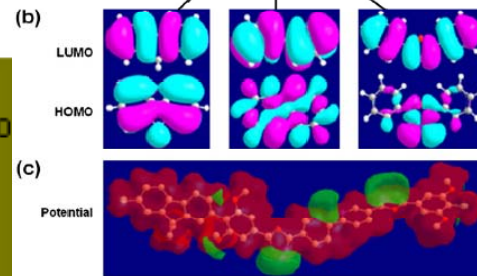
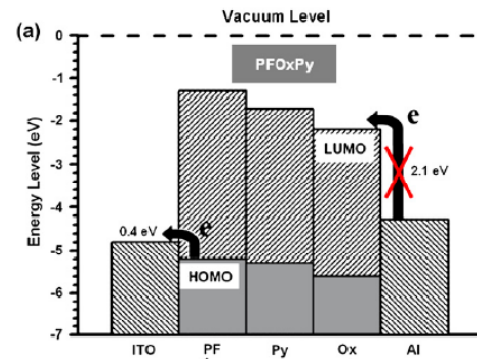
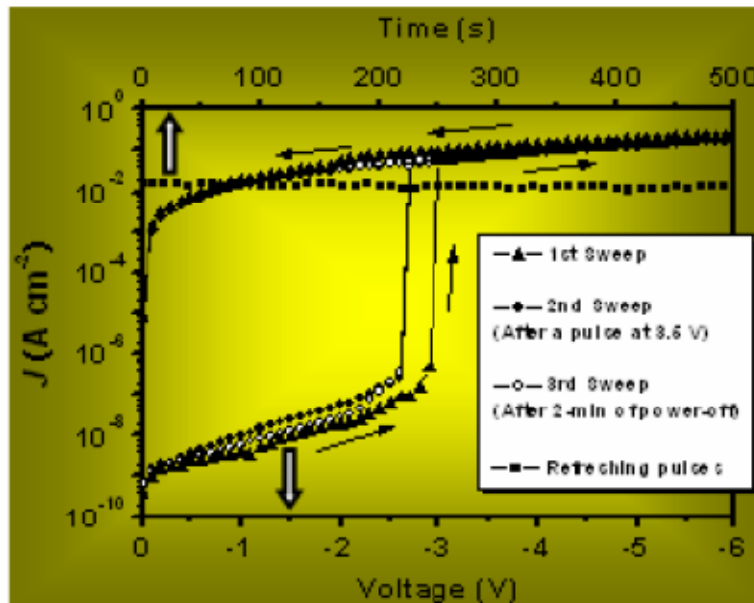
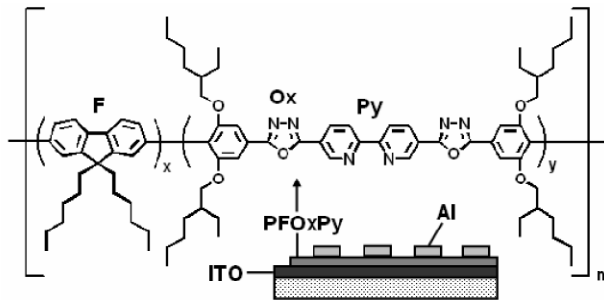
TABLE 1. Effective Distance between Neighboring CNTs in the PVK-CNT Composite Films and the Corresponding Device Behavior (Diameter of CNT = 15 nm)

CNT content (weight percentage)	effective distance (nm)	device type
0.2%	150	insulator
1%	30	WORM memory
2%	15	rewritable memory
3%	10	conductor

# Resistive Random Access Memory (RRAM)

## RRAM from Space Charges and Traps

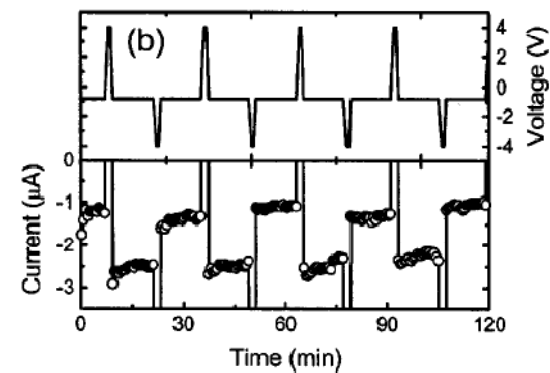
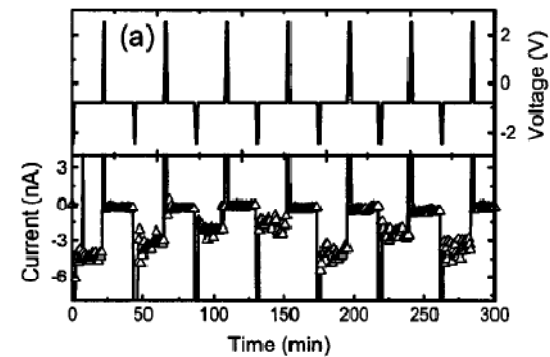
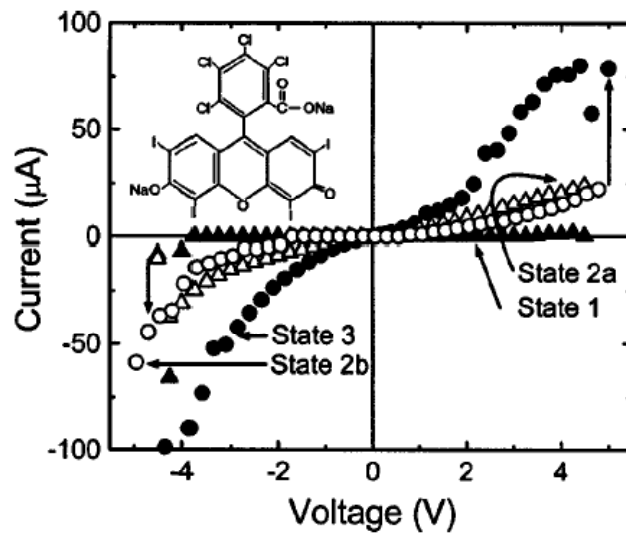
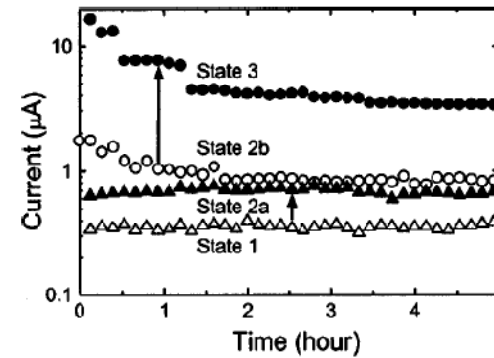
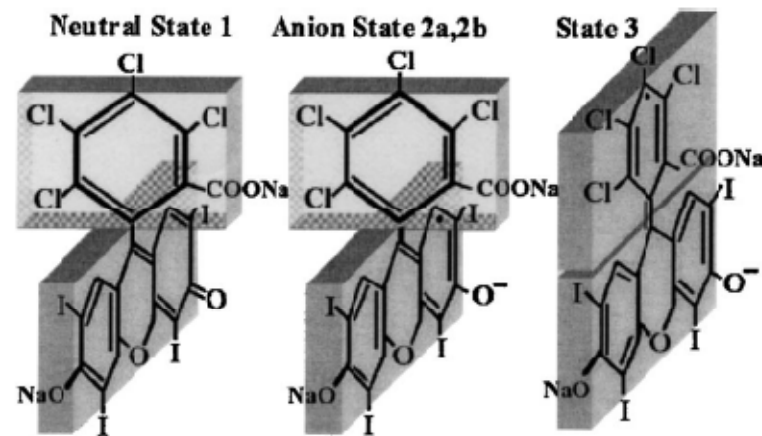
### Dynamic Random Access Memory (DRAM)



*Angew Chem Int Ed* 2006 45 2947

# Resistive Random Access Memory (RRAM)

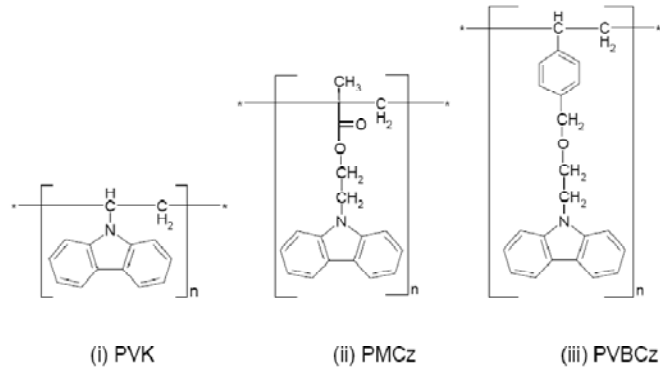
## RRAM from Conformation Change Effects



A J Pal et al. *Appl Phys Lett* 2004 84 999

# Resistive Random Access Memory (RRAM)

## RRAM from Conformation Change Effects



None

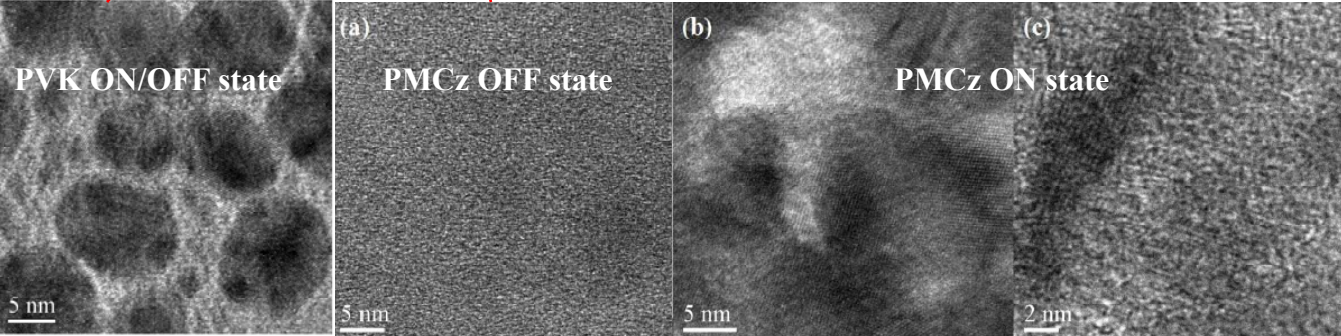
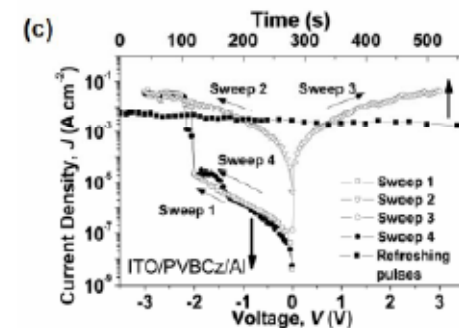
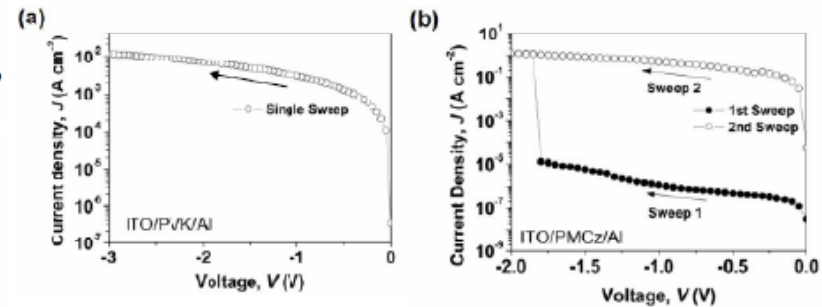
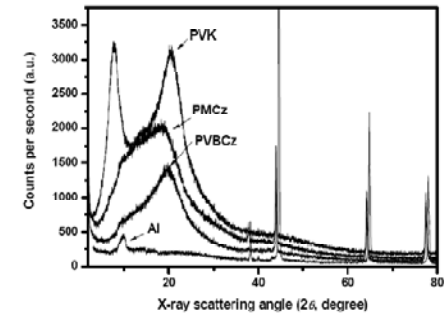
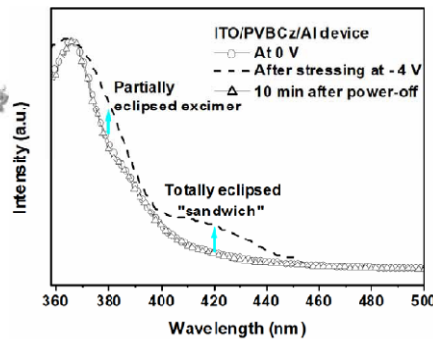
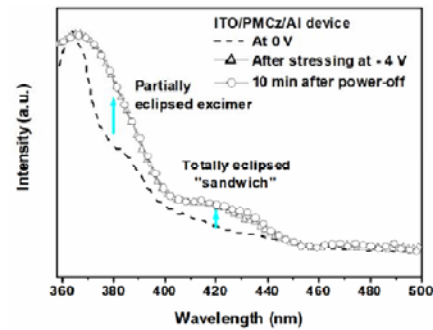
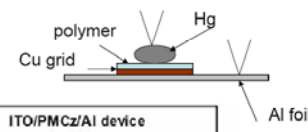
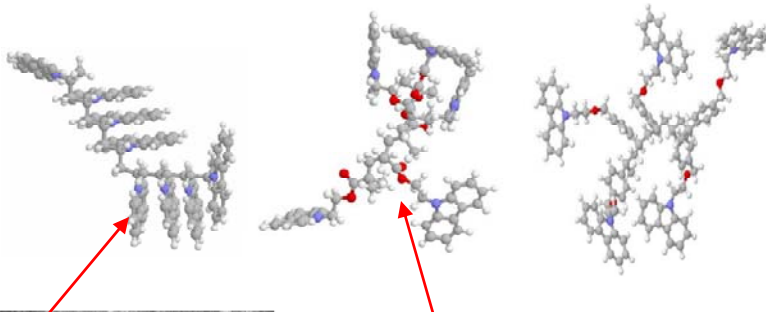
WORM

Volatile

PVK

PMCz

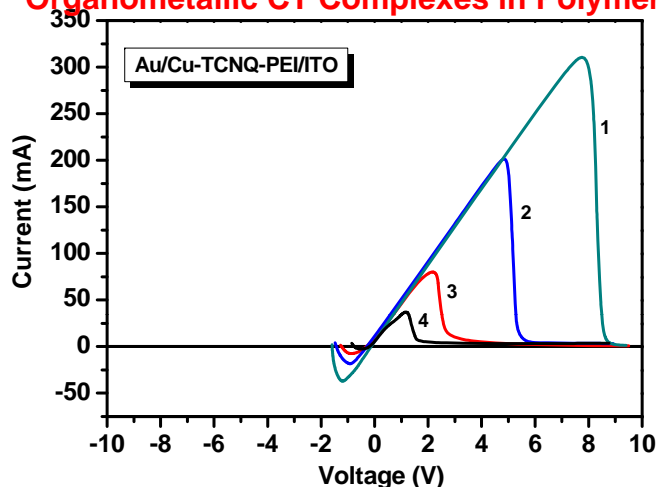
PVBCz



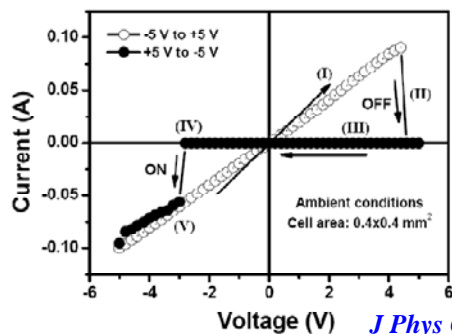
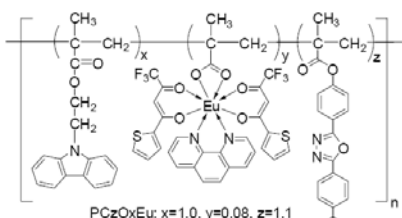
# Resistive Random Access Memory (RRAM)

## RRAM from Charge Transfer (CT) Effects

### Organometallic CT Complexes in Polymers

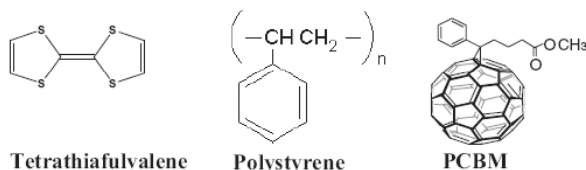


Gong & Osada, *Appl Phys Lett* 1992 61 2787

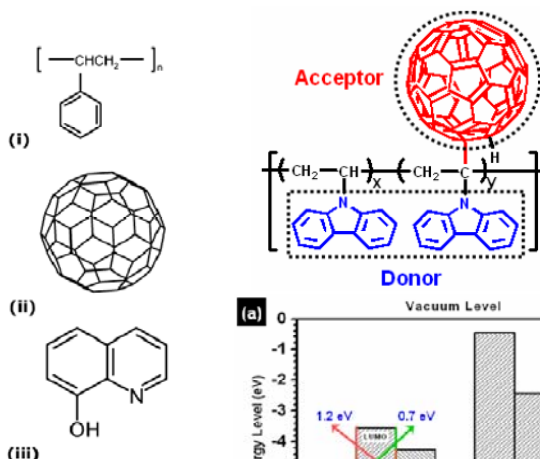


*J Phys Chem B* 2006 110 23995

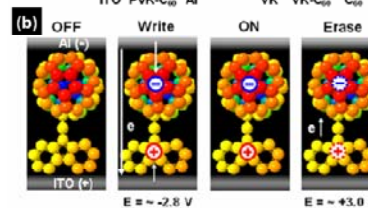
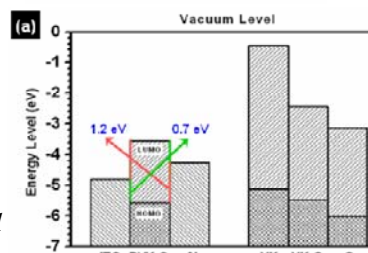
### Rewritable D-A(C<sub>60</sub>) Complexes



Y Yang et al. *Adv Mater* 2005 17 1440

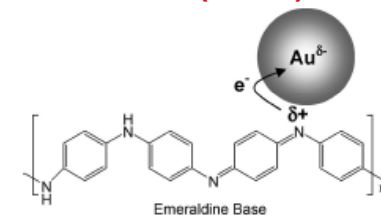


S Paul, *IEEE Trans Nanotechnol* 2007 6 191

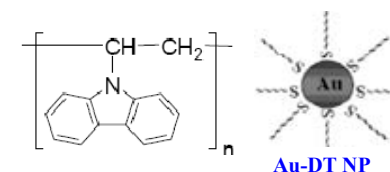


*Langmuir* 2007 23 312

### Rewritable D-A(AuNP) Complexes

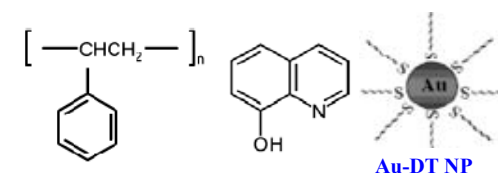


Y Yang et al. *Nano Lett* 2005 5 1077



Au-DT NP

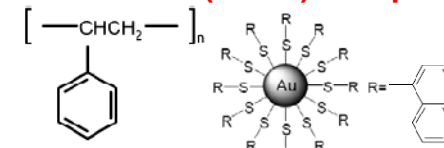
*IEEE Electron Dev Lett* 2007 28 107



Au-DT NP

Y Yang et al. *Nature Mater* 2004 3 918

### WORM D-A(AuNP) Complexes

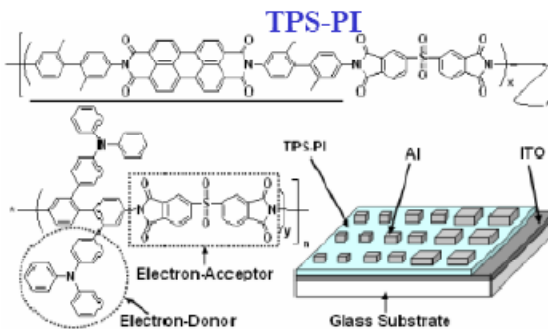
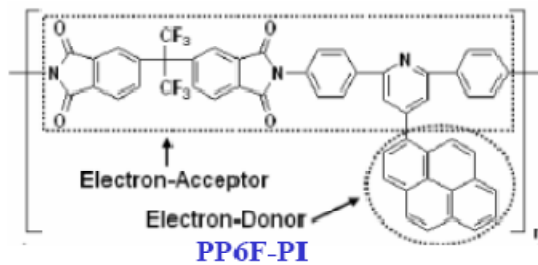
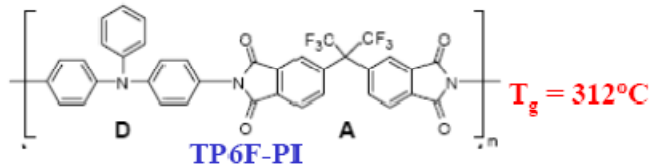


Y Yang et al. *Appl Phys Lett* 2005 86 123507

# Resistive Random Access Memory (RRAM)

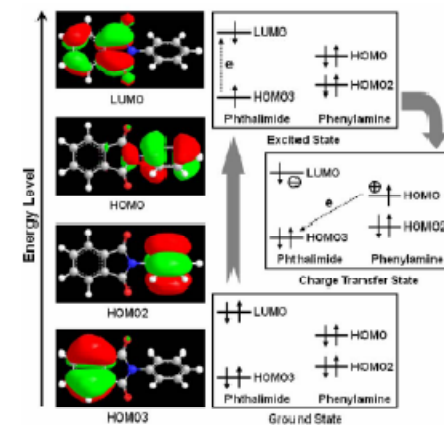
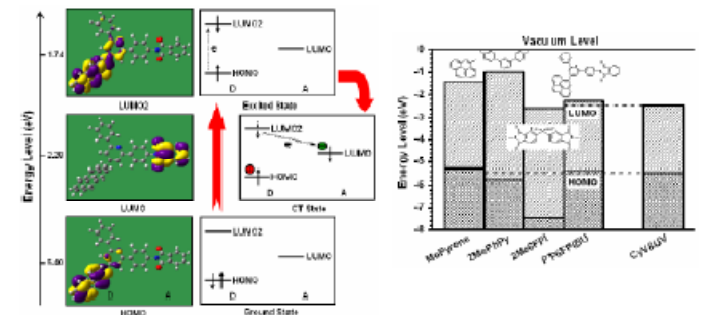
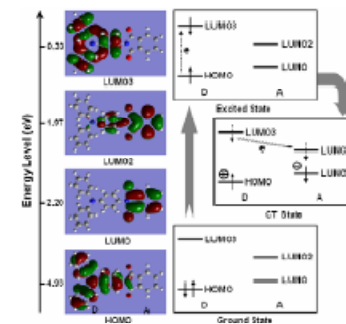
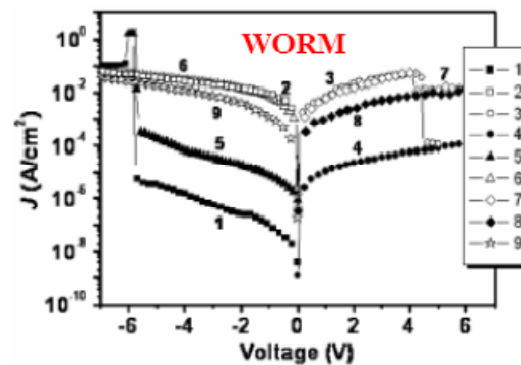
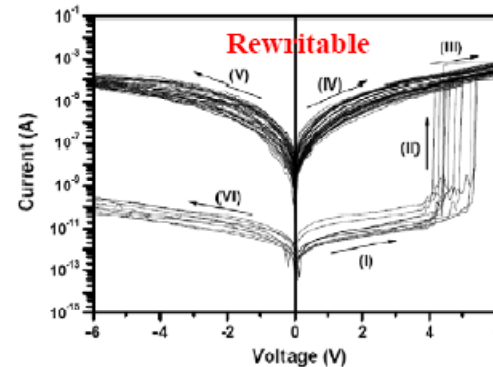
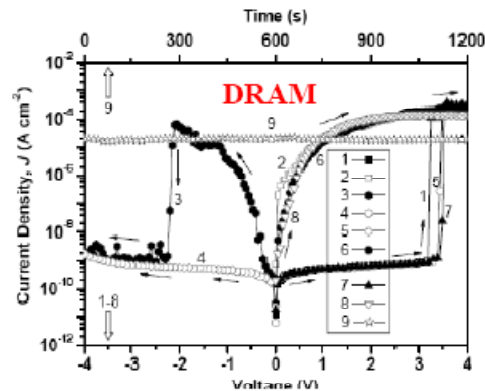
## RRAM from Charge Transfer (CT) Effects

Functional Polyimides Containing Electron Donor(D) and Acceptor(A) Moieties



*J Am Chem Soc* 2006 128 8732

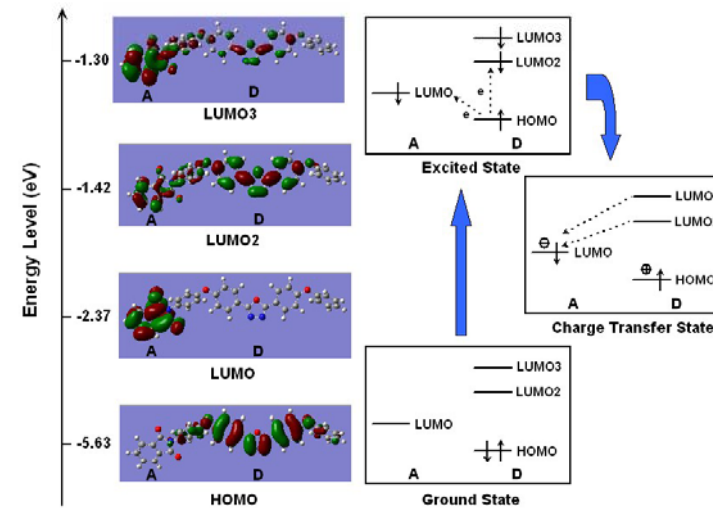
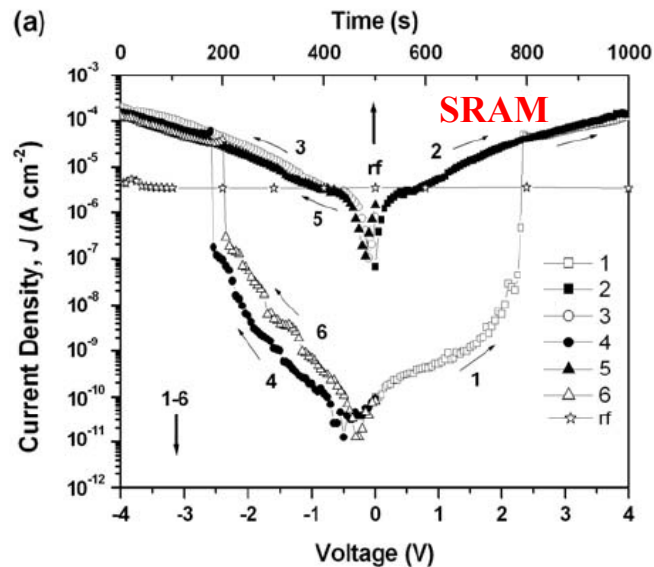
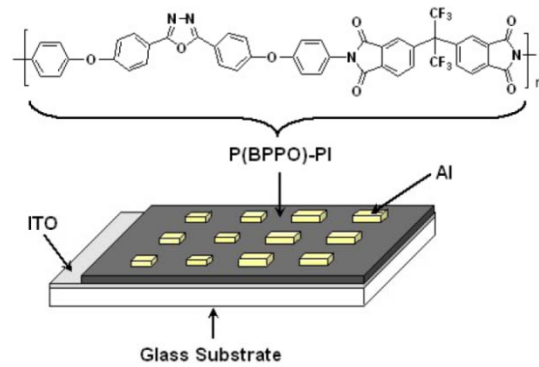
*Polymer* 2007 48 5182 (Feature art.)

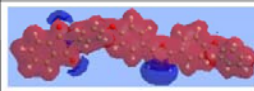
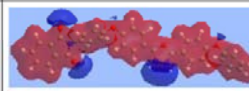
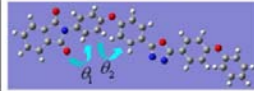
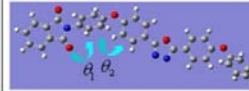


# Resistive Random Access Memory (RRAM)

## RRAM from Charge Transfer (CT) Effects Static Random Access Memory (SRAM)

Functional Polyimides Containing Electron Donor(D) and Acceptor(A) Moieties



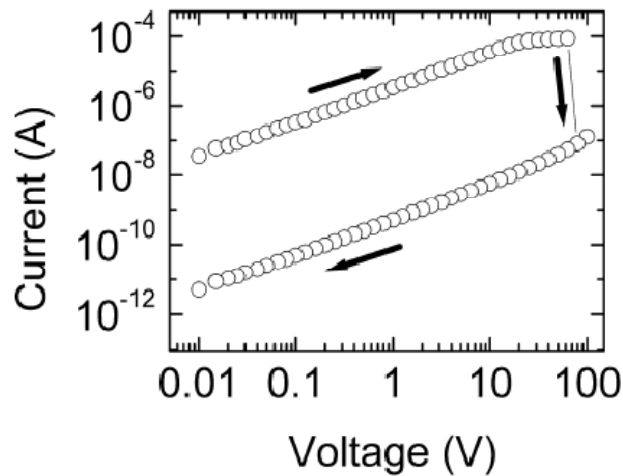
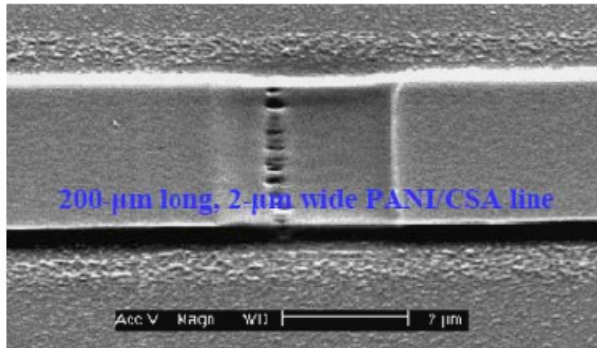
Properties	Ground State	Excited State
Dipole Moment	2.82 Debye	3.06 Debye
ESP Surface		
Optimized Geometry		
Dihedral Angle	$\theta_1 = 40.1^\circ, \theta_2 = 67.1^\circ$	$\theta_1 = 54.6^\circ, \theta_2 = 72.7^\circ$



# Resistive Random Access Memory (RRAM)

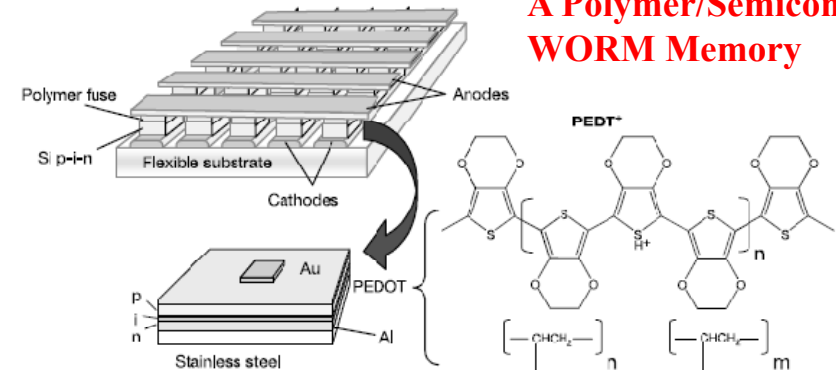
## RRAM from Polymer Fuse Effects

### Doped Polyaniline Fuse-ROM

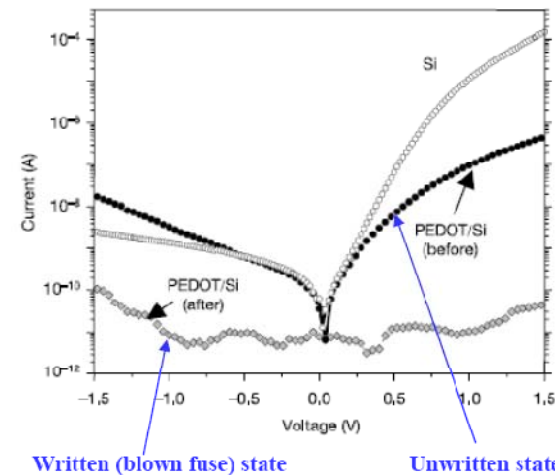


*A W Marsman et al. J Mater Res 2004 19 2057*

The working mechanism relies on irreversible reduction of the electrical conductivity by Joule heating like electrical safety fuses.



### A Polymer/Semiconductor WORM Memory



*S Forrest et al.  
Nature 2003 426 166  
Appl Phys Lett 2006  
89 142109*

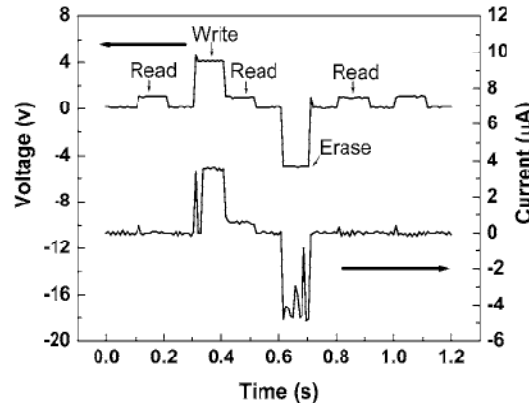
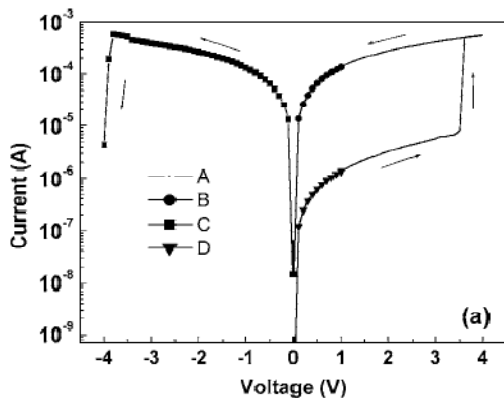
The WORM memory pixel exploits a mechanism of current-controlled, thermally activated un-doping of a two-component electrochromic conducting polymer (PEDOT)

The ratio of PEDT+ to PSS- near the interface changes due to phase segregation in the presence of the applied high field, leading to a decrease in film conductivity by 6 orders

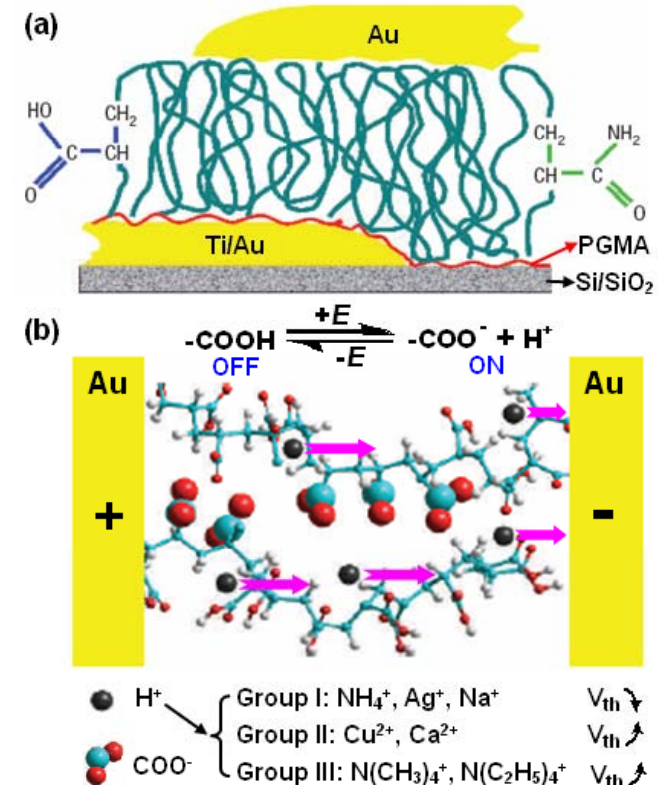
# Resistive Random Access Memory (RRAM)

## RRAM from Ionic Conductions

Al
Ag
RbAg <sub>4</sub> I <sub>5</sub>
MEH-PPV
Pt
SiO <sub>2</sub>



The conductance switching is attributed to the injection/depletion of iodide dopant ions in the MEH-PPV layer by the applied electric field

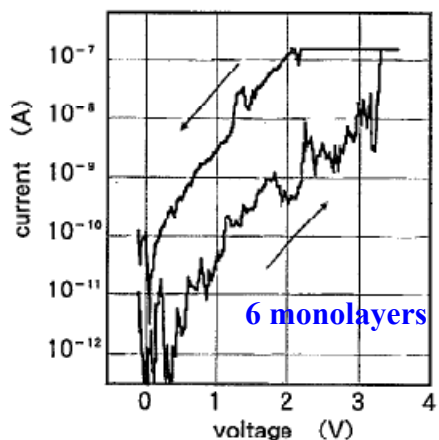
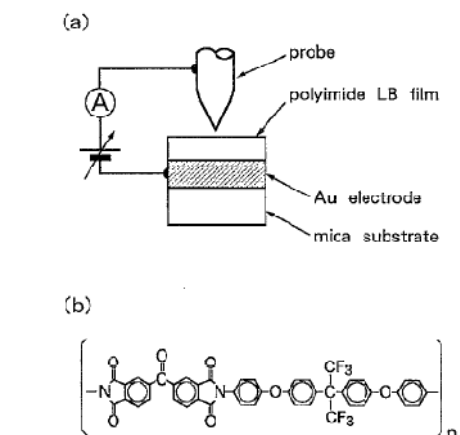


The electronic levels are created by ionization of carboxyl groups. Cations are separated but not completely removed from the system. The conductive channel is formed by a chain of COO<sup>-</sup> anions. An electric field of opposite polarity, which forces cations back, facilitates the recombination of the ionized centres in the conducting channel

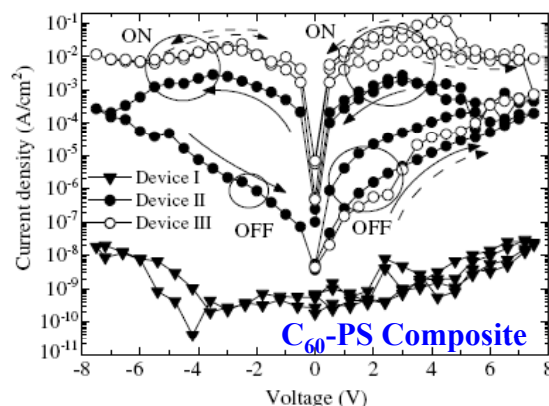
# Resistive Random Access Memory (RRAM)

## RRAM from Tunneling Effects

### Memory Switching in LB Film with STM

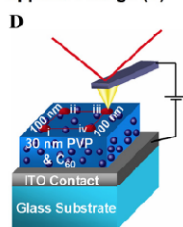
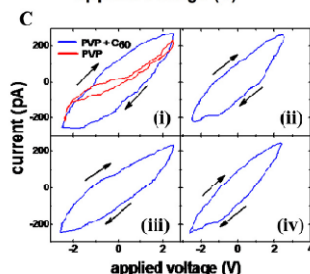
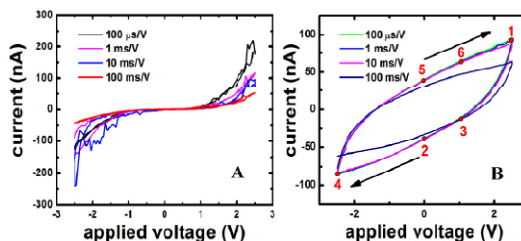


*K Takimoto Appl Phys Lett 1992 61 3032*



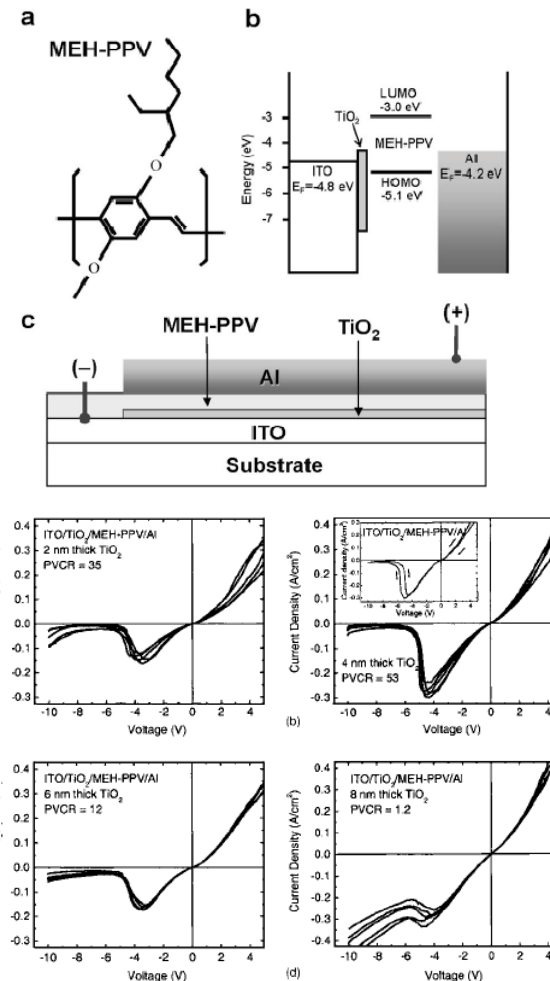
Device I: C<sub>60</sub>(wt)=1.0-5.0%, an insulator  
 Device II: C<sub>60</sub>(wt)=5.0-7.5%, bistable switching)  
 Device III: C<sub>60</sub>(wt)=7.5-20%, WORM)

*H S Majumdar et al. Org Electron 2005 6 188*



*S Paul Nanotechnology 2006 17 145*

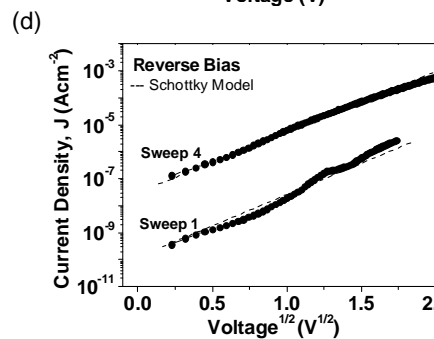
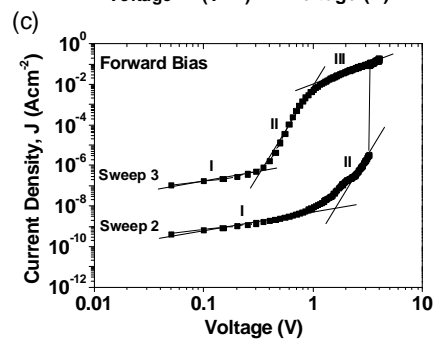
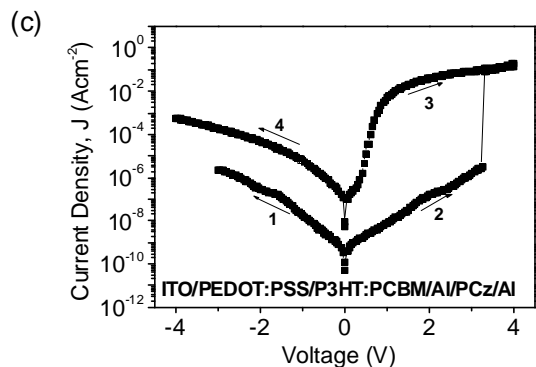
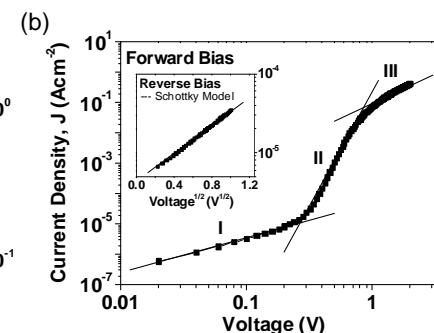
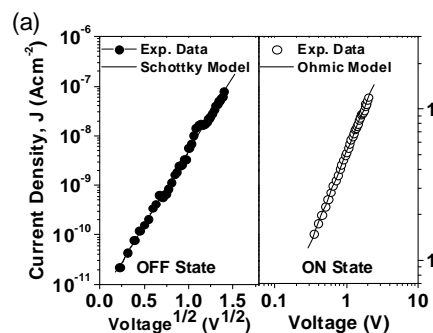
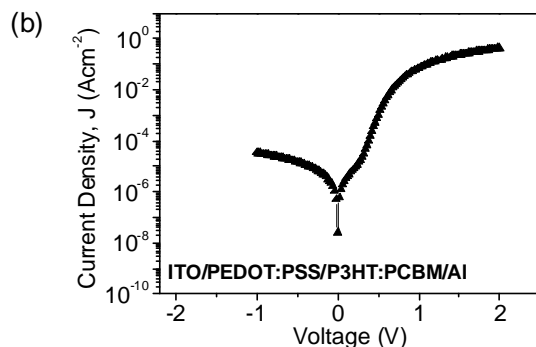
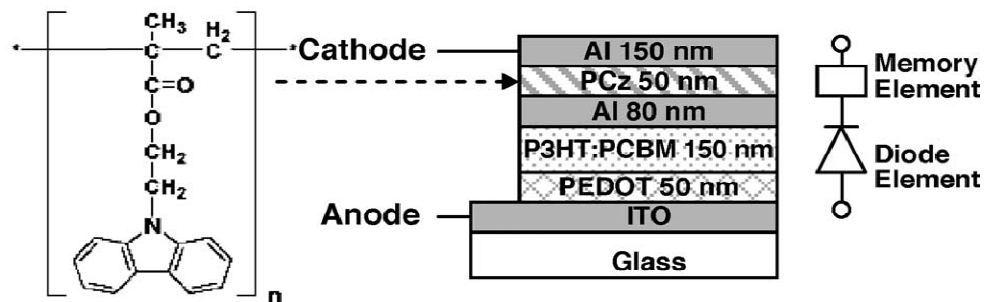
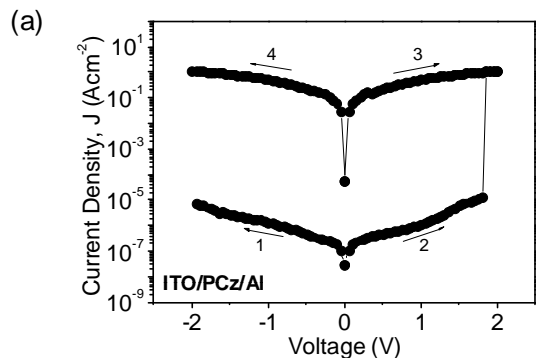
### NDR in MEH-PPV Tunnel Diode



*W J Yoon et al. Appl Phys Lett 2005 87 203506*

# Resistive Random Access Memory (RRAM)

## WORM memory with rectifying property



Thank you!